## REMARKS/ARGUMENT

In accordance with the Examiner's request, enclosed herewith are new formal drawings, which do not have any Japanese language writing thereof. The Examiner's approval of the formal drawings is respectfully requested.

Claims 1-3 stand rejected under 35 U.S.C. §102(b) as being clearly anticipated by either Hanafy (U.S. Patent No. 5,945,770), Smith (U.S. Patent No. 5,548,564), Smith (U.S. Patent No. 5,744,898), Smith (U.S. Patent No. 5,329,496), Lindemann, et al. (U.S. Patent No. 6,066,911) and Obara, et al. (JP 57-193199). Applicants respectfully traverse each of these rejections.

Claim 1 is directed to a sensor array which includes, *inter alia*, a substrate and a plurality of piezoelectric layers laminated in a direction <u>parallel</u> to the main surface of the substrate.

Because the direction of lamination is in a direction <u>parallel</u> to the main surface of the substrate, each of the layers itself is disposed in a direction transverse to the surface of the substrate.

In each of the references, the direction of lamination is in a direction <u>transverse</u> to the surface of the substrate, rather than <u>parallel</u> thereto, as in claim 1, resulting in each of the layers being parallel to the main surface of the substrate.

Thus, in the case of Hanafy, each of the piezoelectric layers 24, 26 and 28 is in respective planes parallel to the main surface of the substrate 22, and, accordingly, the direction of lamination is in a direction <u>transverse</u> to the main surface of the substrate 22, rather than <u>parallel</u> thereto, as in claim 1.

In Smith '564 and '898, each of the piezoelectric layer 24, 26, 28, 30 and 32 is disposed in respective planes parallel to the main surface of the substrate. Thus, the direction of lamination in Smith '564 and Smith '898 is a direction <u>transverse</u> to the main surface of the substrate, rather than <u>parallel</u> thereto, as in claim 1.

In Smith '496, the piezoelectric layers 24, 26, 28, 30 and 32 are disposed in respective planes parallel to the main surface of the substrate. Accordingly, the direction of lamination in Smith '496 is transverse to the main surface of the substrate, rather than <u>parallel</u> thereto, as in claim 1.

In Lindemann, et al., the plurality of piezoelectric layers 10 are disposed in respective planes parallel to the main surface of the substrate. Thus, in Lindemann, et al. the direction of lamination is <u>transverse</u> to the main surface of the substrate, rather than <u>parallel</u> thereto, as set forth in claim 1.

In Obara, et al., the plurality of piezoelectric layers  $3_1$ - $3_n$  are disposed in respective planes parallel to the main surface of the substrate. Accordingly, Obara, et al. discloses lamination in a direction <u>transverse</u> to the main surface of the substrate, rather than in a direction <u>parallel</u> thereto, as set forth in claim 1.

Thus, each of the references applied against claim 1 disclose lamination in a direction transverse to the main surface of the substrate, rather than <u>parallel</u> thereto, as in claim 1. Further, none of the references suggest that the layers be laminated in a direction <u>parallel</u> to the surface of the substrate. Accordingly, it is respectfully submitted that claim 1 is not only not anticipated by the references, but is not rendered obvious thereby.

Claims 2 and 3 incorporate the <u>parallel</u> direction of lamination of claim 1, and are, therefore, patentable for the same reasons, as well as because of the combination of the features set forth in these claims with the <u>parallel</u> direction of lamination.

In view of the foregoing, this application is now believed to be in condition for allowance, which action is respectfully requested.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on April 3, 2002:

Martin Pfeffer

Name of applicant, assignee or Registered Representative

Signature April 3, 2002

Date of Signature

Respectfully submitted,

Martin Pfeffer

Registration No.: 20,808

OSTROLENK, FABER, GERB & SOFFEN, LLP

1180 Avenue of the Americas

New York, New York 10036-8403

Telephone: (212) 382-0700

MP:jy